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Circuits and Systems II: Analog and Digital Signal Processing, IEEE Transactions on [see also Circuits and Systems II: Express Briefs, IEEE Transactions on] , Vol 48 , Issue: 5 , May 2001

Pages:492 - 500

[Abstract] [PDF Full-Text (196 KB)] IEEE JNL

2 Three-dimensional inspection of ball grid array using laser vision system*Pyunghyun Kim; Sehun Rhee;*

Electronics Packaging Manufacturing, IEEE Transactions on [see also Component Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on] , Volume: 22 , Issue: 2 , April 1999

Pages:151 - 155

[Abstract] [PDF Full-Text (152 KB)] IEEE JNL

3 A tree-matching chip*Krishna, V.; Ranganathan, N.; Ejnoui, A.;*

Very Large Scale Integration (VLSI) Systems, IEEE Transactions on , Volume: 7 , Issue: 2 , June 1999

Pages:277 - 280

[Abstract] [PDF Full-Text (128 KB)] IEEE JNL

4 The graph search machine (GSM): A programmable processor for connected word speech recognition and other applications*Glinski, S.; Lalumia, T.; Cassidy, D.; Taiho Koh; Gerveshi, C.; Wilson, G.; Kim, J.;*

Acoustics, Speech, and Signal Processing, IEEE International Conference on
ICASSP '87. , Volume: 12 , Apr 1987
Pages:519 - 522

[\[Abstract\]](#) [\[PDF Full-Text \(152 KB\)\]](#) IEEE CNF

5 In-situ reliability analysis of solder joint by digital image correlation

Pang, J.H.L.; Zhang, X.K.; Liu, Q.J.; Che, F.X.; Low, T.H.; Shi, X.Q.; Wang, Z
Electronics Packaging Technology Conference, 2002. 4th , 10-12 Dec. 2002
Pages:115 - 119

[\[Abstract\]](#) [\[PDF Full-Text \(1087 KB\)\]](#) IEEE CNF

6 Conjunction search using a 1-D, analog VLSI-based, attentional search/tracking chip

Horiuchi, T.; Niebur, E.;
Advanced Research in VLSI, 1999. Proceedings. 20th Anniversary Conference
on , 21-24 March 1999
Pages:276 - 290

[\[Abstract\]](#) [\[PDF Full-Text \(932 KB\)\]](#) IEEE CNF

7 Thermal resistance degradation of alloy die attached power devices during thermal cycling

Naderman, J.; Ragay, F.W.; De Vries, D.G.; Van Eck, A.; Van de Water, J.;
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1 Analysis of Surface Mount Thermal and Thermal Stress Performance

Waller, D.; Fox, L.; Hannemann, R.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C] ; Volume: 6 , Issue: 3 , Sep 1983
 Pages:257 - 266

[\[Abstract\]](#) [\[PDF Full-Text \(1688 KB\)\]](#) IEEE JNL

2 Thermal Characterization of Plastic and Ceramic Surface-Mount Components

Furkay, S.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C] , Volume: 11 , Issue: 4 , Dec 1988
 Pages:521 - 527

[\[Abstract\]](#) [\[PDF Full-Text \(896 KB\)\]](#) IEEE JNL

3 Stress Analysis of Partially Yielded Soldered Joint for Surface Mount Connectors

Yamada, S.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C] , Volume: 10 , Issue: 2 , Jun 1987
 Pages:236 - 241

[\[Abstract\]](#) [\[PDF Full-Text \(696 KB\)\]](#) IEEE JNL

4 Elastoplastic Analysis of Surface-Mount Solder Joints

Lau, J.; Rice, D.; Avery, P.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C] , Volume: 10 , Issue: 3 , Sep 1987

Pages:346 - 357

[\[Abstract\]](#) [\[PDF Full-Text \(1320 KB\)\]](#) IEEE JNL

5 Solderability Degradation Models for Fusible Tin Alloy Coatings on Copper Substrates

Geist, H.; Kottke, M.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [also IEEE Trans. on Components, Packaging, and Manufacturing Technology, A, B, C] , Volume: 11 , Issue: 3 , Sep 1988

Pages:270 - 273

[\[Abstract\]](#) [\[PDF Full-Text \(520 KB\)\]](#) IEEE JNL

6 Analytical models for exterior-type permanent magnet synchronous motors

Rahman, M.;

Magnetics, IEEE Transactions on , Volume: 23 , Issue: 5 , Sep 1987

Pages:3625 - 3627

[\[Abstract\]](#) [\[PDF Full-Text \(264 KB\)\]](#) IEEE JNL

7 Formation and growth kinetics of interfacial intermetallics in Pb-free solder joint

Li, G.Y.; Chen, B.L.;

Components and Packaging Technologies, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on] , Volume: 26 , Issue: 3 , Sept. 2003

Pages:651 - 658

[\[Abstract\]](#) [\[PDF Full-Text \(925 KB\)\]](#) IEEE JNL

8 Heat transfer analysis and simplified thermal resistance modeling of linear motor driven stages for SMT applications

Chanhgsoo Jang; Jong Young Kim; Yung Joon Kim; Jae Ok Kim;

Components and Packaging Technologies, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on] , Volume: 26 , Issue: 3 , Sept. 2003

Pages:532 - 540

[\[Abstract\]](#) [\[PDF Full-Text \(1224 KB\)\]](#) IEEE JNL

9 Thermal management of BioMEMS: temperature control for ceramic based PCR and DNA detection devices

Sadler, D.J.; Changrani, R.; Roberts, P.; Chia-Fu Chou; Zenhausern, F.;

Components and Packaging Technologies, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on] , Volume: 26 , Issue: 2 , June 2003

Pages:309 - 316

[\[Abstract\]](#) [\[PDF Full-Text \(1782 KB\)\]](#) IEEE JNL

10 Analytical model for permanent magnet motors with surface mounted magnets

Proca, A.B.; Keyhani, A.; El-Antably, A.; Wenzhe Lu; Min Dai;

Energy Conversion, IEEE Transactions on , Volume: 18 , Issue: 3 , Sept. 2003
Pages:386 - 391

[\[Abstract\]](#) [\[PDF Full-Text \(518 KB\)\]](#) IEEE JNL

11 Optimizing the operation sequence of a chip placement machine using TSP model

Kumar, R.; Zhonghui Luo;

Electronics Packaging Manufacturing, IEEE Transactions on [see also Component Packaging and Manufacturing Technology, Part C: Manufacturing, IEEE Transactions on] , Volume: 26 , Issue: 1 , Jan. 2003
Pages:14 - 21

[\[Abstract\]](#) [\[PDF Full-Text \(515 KB\)\]](#) IEEE JNL

12 Lumped-circuit model extraction for vias in multilayer substrates

Jun Fan; Drewniak, J.L.; Knighten, J.L.;

Electromagnetic Compatibility, IEEE Transactions on , Volume: 45 , Issue: 2 , 2003
Pages:272 - 280

[\[Abstract\]](#) [\[PDF Full-Text \(699 KB\)\]](#) IEEE JNL

13 Optimization of electromagnetic absorption in laminated composite plates

Matous, K.; Dvorak, G.J.;

Magnetics, IEEE Transactions on , Volume: 39 , Issue: 3 , May 2003
Pages:1827 - 1835

[\[Abstract\]](#) [\[PDF Full-Text \(925 KB\)\]](#) IEEE JNL

14 Evolution toward standardized market design

Xingwang Ma; Sun, D.I.; Cheung, K.W.;

Power Systems, IEEE Transactions on , Volume: 18 , Issue: 2 , May 2003
Pages:460 - 469

[\[Abstract\]](#) [\[PDF Full-Text \(254 KB\)\]](#) IEEE JNL

15 Tubular linear permanent magnet motors: an overall comparison

Bianchi, N.; Bolognani, S.; Corte, D.D.; Tonel, F.;

Industry Applications, IEEE Transactions on , Volume: 39 , Issue: 2 , March-April 2003
Pages:466 - 475

[\[Abstract\]](#) [\[PDF Full-Text \(711 KB\)\]](#) IEEE JNL

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DOCUMENT-IDENTIFIER: US 6078700 A

TITLE: Method and apparatus for location and inspecting a two-dimensional image including co-linear features

Brief Summary Text (12):

The grouping technique for searching for correspondence between model features and image features involves using a small, selected subset of image features. The image features selected for determining correspondence with model features are ones that are most likely to belong to a subset of a set of features comprising the model. For example, a vision system might be implemented in an application wherein it is desirable to find a particular rectangular object in the scene or image, e.g. a microchip. Although the captured image contains many objects, grouping could be applied by having the vision system select all groups of line segments from the image, and more particularly all groups of line segments that are at right angles to each other. The subsets or smaller groups of features, e.g. line segments at right angles to each other, would then be used to match to the chip model, rather than using the entire set of line segments.